



Material Content Data Sheet



Sales Product Name	TLE9832QV			Issued		28. August 2013		
MA#	MA000950714							
Package	PG-VQFN-48-22			Weight*		133.19 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.983	3.74	3.74	37414	37414
leadframe	inorganic material	phosphorus	7723-14-0	0.020	0.01		149	
	non noble metal	zinc	7440-66-6	0.079	0.06		595	
	non noble metal	iron	7439-89-6	1.585	1.19		11903	
	non noble metal	copper	7440-50-8	64.371	48.33	49.59	483300	495947
wire	noble metal	gold	7440-57-5	0.778	0.58	0.58	5841	5841
encapsulation	organic material	carbon black	1333-86-4	0.168	0.13		1264	
	plastics	epoxy resin	-	7.126	5.35		53503	
	inorganic material	silicondioxide	60676-86-0	48.816	36.65	42.13	366513	421280
leadfinish	non noble metal	tin	7440-31-5	2.385	1.79	1.79	17908	17908
plating	noble metal	silver	7440-22-4	1.633	1.23	1.23	12264	12264
glue	plastics	epoxy resin	-	0.286	0.22		2150	
	noble metal	silver	7440-22-4	0.958	0.72	0.94	7196	9346
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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